12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN 20160908002
Assembly and Test site move from MLA to PTIAT for Select Devices
Change Notification

Date: 9/19/2016
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20160908002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMZ31710RVQR	null
LMZ31710RVQT	null
LMZ31707RVQT	null

Technical details of this Product Change follow on the next pages.

PCN Number:	20160908002	**PCN Date:**	Sept 19, 2016
Title:	Assembly and Test site move from MLA to PTIAT for Select Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Dec 19, 2016	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the Assembly and Test site move from MLA to PTIAT for Select Devices listed in the "Product Affected" Section. No Material differences between Sites.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
TI Malaysia	MLA	MY	Kuala Lumpur
Powertech Technology Inc.	**PT2**	**TW**	**Hsinchu City**

Test coverage, insertions, conditions will remain consistent with current testing and verified via test MQ.

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

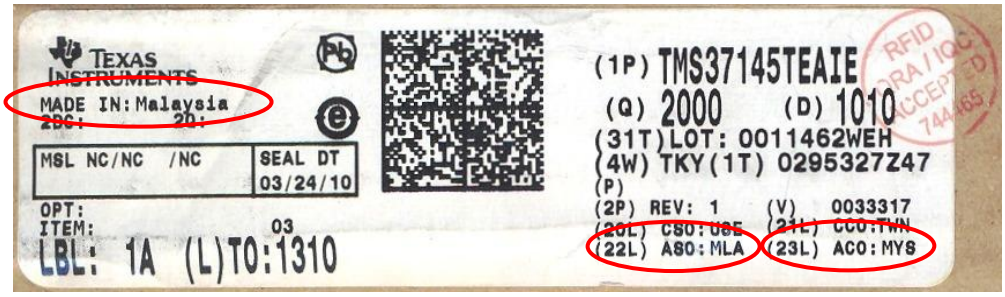
Changes to product identification resulting from this PCN:

Sample product shipping label (not actual product label)

Assembly Site:

TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
Powertech Technology Inc.	Assembly Site Origin (22L)	ASO: PT2

Sample product shipping label to show code location (not actual product label)



ASSEMBLY SITE CODES: MLA=K, PT2 =C

Products Affected

LMZ31704RVQR	LMZ31707RVQR	LMZ31710RVQR	TPS84A20RVQR
LMZ31704RVQT	LMZ31707RVQT	LMZ31710RVQT	TPS84A20RVQT

TEXAS INSTRUMENTS

Qualification Report

LMZ31704RVQ, LMZ31707RVQ, LMZ31710RVQ
Approve Date 22-Aug-2016

Product Attributes

Attributes	Qual Device: LMZ31710RVQ	QBS Product Family: LMZ31704RVQ	QBS Product Family: LMZ31707RVQ	QBS Product Reference: LMZ31710RVQ	QBS Package Reference: LMZ36002RVQ
Die Attributes	-	-	-		
Wafer Fab Supplier	TI – Germany	TI - Germany	TI - Germany	TI - Germany	DMOS5
Wafer Process	LBC7	LBC7	LBC7	LBC7	LBC8
Assembly Site	PTI-Taiwan	PTI-Taiwan	PTI-Taiwan	TI - Malaysia	PTI-Taiwan
Package Family	QFN	QFN	QFN	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0

- QBS: Qual By Similarity
- Qual Device LMZ31704RVQ, LMZ31707RVQ, LMZ31710RVQ are qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMZ31710RVQ	QBS Product Reference: LMZ31710RVQ	QBS Package Reference: LMZ36002RVQ
PC	Preconditioning Level 3	260C	1/231/0	-	3/231/0
HTOL	Life Test, 125C	1000 hours	1/77/0	2/154/0	-
PTCL	Power Temperature Cycle, 25C/70C	1000 hours	1/40/0	-	-
HTSL	High Temp Storage Bake 150C	1000 hours	1/77/0	-	1/77/0
TC	Temperature Cycle, -65/150C	500 cycles	1/77/0	-	-
TC	Temperature Cycle, -55/125C	700 cycles	-	-	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 hours	1/77/0	-	1/77/0
UHAST	Unbiased HAST 110C/85%RH	264 hours	1/77/0	-	3/231/0
HBM	ESD HBM	1500V	-	0/3	-
CDM	ESD CDM	750V	-	0/3	-
ED	Electrical Characterization	-	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com